RELIABILITY REPORT
FOR
MAX4644EUA+
PLASTIC ENCAPSULATED DEVICES

November 3, 2008

MAXIM INTEGRATED PRODUCTS
120 SAN GABRIEL DR.
SUNNYVALE, CA 94086

Approved by
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Quality Assurance
Director, Reliability Engineering
Conclusion

The MAX4644EUA+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

Table of Contents

I. Device Description V. Quality Assurance Information
II. Manufacturing Information VI. Reliability Evaluation
III. Packaging Information IV. Die Information
.....Attachments

I. Device Description

A. General

The MAX4644 is a single-pole/double-throw (SPDT) switch that operates from a single supply ranging from +1.8V to +5.5V. It provides low on-resistance (RON) as well as RON flatness over the entire analog signal range. The MAX4644 offers fast switching times of less than 20ns while ensuring break-before-make operation. It typically consumes only 0.01µW of quiescent power, making it suitable for use in low-power, portable applications. The MAX4644's features include low leakage currents over the entire temperature range, TTL/CMOS-compatible digital logic, and excellent AC characteristics. It is packaged in either a small 8-pin μMAX® or a tiny 6-pin SOT23.
II. Manufacturing Information

A. Description/Function: High-Speed, Low-Voltage, 4 Ohm, Dual, SPDT CMOS Analog Switch
B. Process: 0.5 um CMOS
C. Number of Device Transistors:
D. Fabrication Location: Taiwan
E. Assembly Location: UTL Thailand, Unisem Malaysia
F. Date of Initial Production: April 22, 2000

III. Packaging Information

A. Package Type: 8-pin uMAX
B. Lead Frame: Copper
C. Lead Finish: 100% matte Tin
D. Die Attach: Conductive Epoxy
E. Bondwire: Gold (1 mil dia.)
F. Mold Material: Epoxy with silica filler
G. Assembly Diagram: #05-1201-0161
H. Flammability Rating: Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C Level 1
J. Single Layer Theta Ja: 221°C/W
K. Single Layer Theta Jc: 41.9°C/W
L. Multi Layer Theta Ja: 206.3°C/W
M. Multi Layer Theta Jc: 41.9°C/W

IV. Die Information

A. Dimensions: 50 X 35 mils
B. Passivation: Oxide / Nitride
C. Interconnect: Al/Cu
D. Backside Metallization: None
E. Minimum Metal Width: 0.5 um
F. Minimum Metal Spacing: 0.5 um
G. Bondpad Dimensions: 5 mil. Sq.
H. Isolation Dielectric: Silicon Dioxide
I. Die Separation Method: Saw
V. Quality Assurance Information

A. Quality Assurance Contacts:
   - Ken Wendel (Director, Reliability Engineering)
   - Bryan Preeshl (Managing Director of QA)

B. Outgoing Inspection Level:
   - 0.1% for all electrical parameters guaranteed by the Datasheet.
   - 0.1% for all Visual Defects.

C. Observed Outgoing Defect Rate:
   - < 50 ppm

D. Sampling Plan:
   - Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

   The results of the 135 biased (static) life test are pending. Using these results, the Failure Rate (\( \lambda \)) is calculated as follows:

   \[
   \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 240 \times 2}
   \]

   (Chi square value for MTTF upper limit)

   \[
   \lambda = 4.5 \times 10^9
   \]

   \[
   \lambda = 4.5 \text{ F.I.T. (60% confidence level @ 25°C)}
   \]

   The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at [http://www.maxim-ic.com/](http://www.maxim-ic.com/). Current monitor data for the TSMC 0.5um Process results in a FIT Rate of 4.5 @ 25C and 77.5 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

   The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

   The AH42 die type has been found to have all pins able to withstand a HBM transient pulse of <500 V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of 250 mA.
### Table 1
Reliability Evaluation Test Results

<table>
<thead>
<tr>
<th>TEST ITEM</th>
<th>TEST CONDITION</th>
<th>FAILURE IDENTIFICATION</th>
<th>SAMPLE SIZE</th>
<th>NUMBER OF FAILURES</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Static Life Test</strong> (Note 1)</td>
<td>Ta = 135°C Biased Time = 192 hrs.</td>
<td>DC Parameters &amp; functionality</td>
<td>240</td>
<td>0</td>
</tr>
<tr>
<td><strong>Moisture Testing</strong> (Note 2)</td>
<td>Ta = 85°C Biased RH = 85% Time = 1000hrs.</td>
<td>DC Parameters &amp; functionality</td>
<td>77</td>
<td>0</td>
</tr>
<tr>
<td><strong>Mechanical Stress</strong> (Note 2)</td>
<td>-65°C/150°C 1000 Cycles Method 1010</td>
<td>DC Parameters &amp; functionality</td>
<td>77</td>
<td>0</td>
</tr>
</tbody>
</table>

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data